

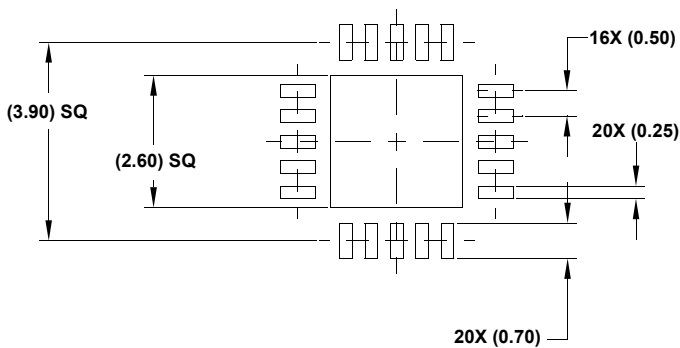
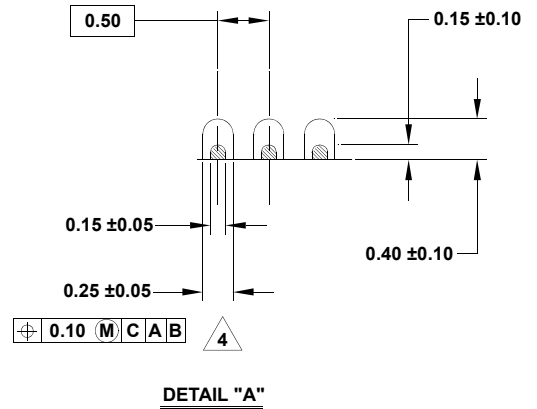
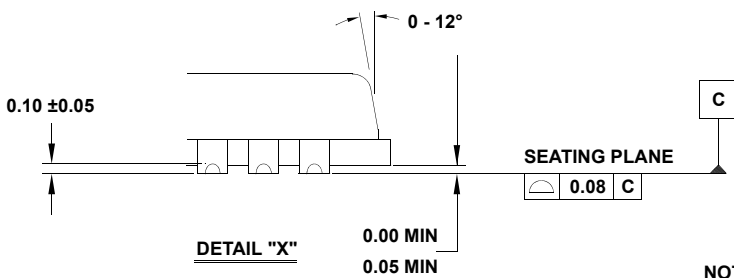
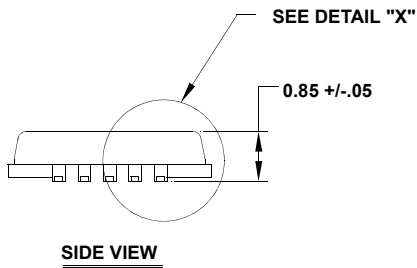
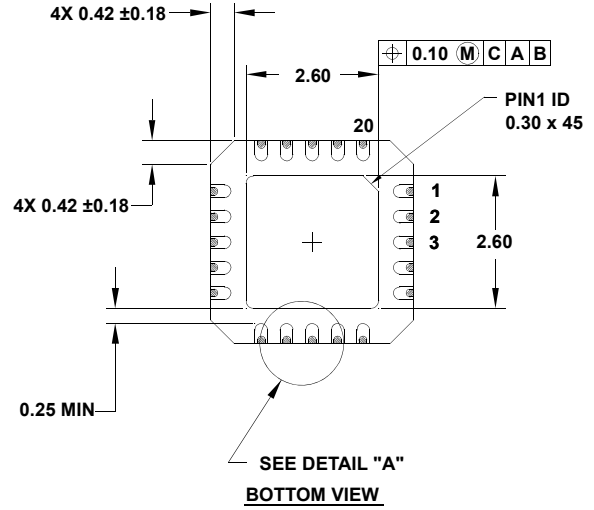
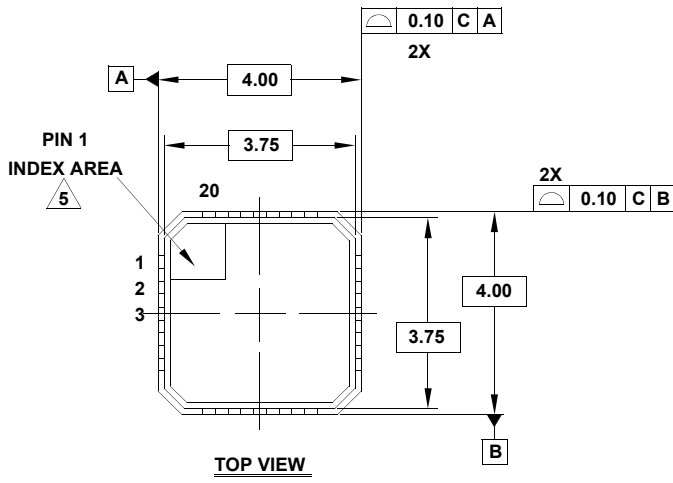
Plastic Packages for Integrated Circuits

Package Outline Drawing

L20.4x4F

20 LEAD QUAD FLAT NO-LEAD PLASTIC PACKAGE (PUNCH QFN WITH WETABLE FLANK)

Rev 0, 2/11



NOTES:

1. Dimensions are in millimeters.
Dimensions in () for Reference Only.
2. Dimensioning and tolerancing conform to ASME Y14.5m-1994.
3. Unless otherwise specified, tolerance : Decimal ± 0.05
4. Dimension applies to the metallized terminal and is measured between 0.20mm and 0.25mm from the terminal tip.
5. The configuration of the pin #1 identifier is optional, but must be located within the zone indicated. The pin #1 identifier may be either a mold or mark feature.
6. Reference document: JEDEC MO220.